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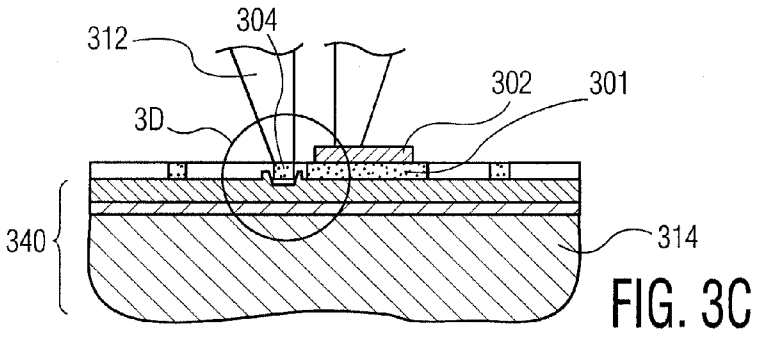


FIG. 3C

(57) Abstract: A support structure for supporting a semiconductor device during a bonding operation is provided. The support structure comprises a body portion defining an upper surface configured to support a semiconductor device during a bonding operation. The upper surface defines a constraining feature for constraining at least a portion of the semiconductor device during the bonding operation.

WO 2012/096638 A2